ABSTRACT

A wafer-dicing adhesive tape, containing two or more removable adhesive layers, on a base film, that have resin compositions containing a radiation-polymerizable compound, in which a content of the radiation-polymerizable compound in the resin composition constituting an outermost removable adhesive layer is different from that of an inner removable adhesive layer and a stress applied to the base film is sufficiently introduced to the outermost removable adhesive layer irradiated with radiation, so that said layer can be easily peeled off from chips cut; and a method of producing chips using the same.